8-Input Data Selector/Multiplexer

High-Performance Silicon-Gate CMOS

The MC74HC151 is identical in pinout to the LS151. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device selects one of the eight binary Data Inputs, as determined by the Address Inputs. The Strobe pin must be at a low level for the selected data to appear at the outputs. If Strobe is high, the Y output is forced to a low level and the \overline{Y} output is forced to a high level.

The HC151 is similar in function to the HC251 which has 3-state outputs.

Features

• Output Drive Capability: 10 LSTTL Loads

• Outputs Directly Interface to CMOS, NMOS, and TTL

• Operating Voltage Range: 2 to 6 V

• Low Input Current: 1 μA

• High Noise Immunity Characteristic of CMOS Devices

• These are Pb-Free Devices

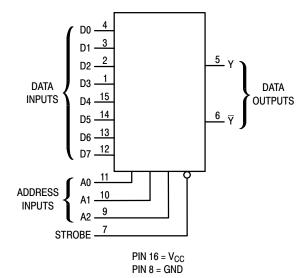
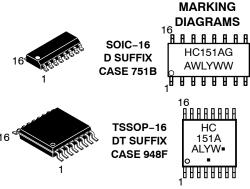


Figure 1. Logic Diagram



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A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G or = Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT							
D3 [1 ●	16	V _{CC}				
D2 [2	15] D4				
D1 [3	14	D5				
D0 [4	13] D6				
ΥC	5	12	D7				
7 [6	11] A0				
ткове [7	10	A1				
GND [8	9	A2				
			-				

FUNCTION TABLE

S

	Inputs			Out	puts	
A2	A 1	A0	Strobe	Υ	Y	
Х	Χ	Χ	Н	L	Н	
L	L	L	L	D0	D0	
L	L	Н	L	D1	D1	
L	Н	L	L	D2	D2	
L	Н	Н	L	D3	D3	
Н	L	L	L	D4	D4	
Н	L	Н	L	D5	D5	
Н	Н	L	L	D6	D6	
Н	Н	Н	L	D7	D7	

D0, D1, ..., D7 = the level of the respective D in-

put. ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value U	Jnit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	٧
V _{in}	DC Input Voltage (Referenced to GND)	-1.5 to V _{CC} + 1.5	٧
V _{out}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	٧
I _{in}	DC Input Current, per Pin	±20 m	mΑ
I _{out}	DC Output Current, per Pin	±25 m	mΑ
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±50 m	mΑ
P _D	Power Dissipation in Still Air SOIC Packet TSSOP Packet	9-	nW
T _{stg}	Storage Temperature	−65 to +150 °	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	٧	
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced	0	V _{CC}	V	
T _A	Operating Temperature, All Package Types	-55	+125	°C	
t _r , t _f	(Figure 2) V _C	_{CC} = 2.0 V _{CC} = 4.5 V _{CC} = 6.0 V	0 0 0	1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Guaranteed Limit			
Symbol	Parameter	Test Conditions	V _{CC}	– 55 to 25°C	≤ 85 °C	≤ 125°C	Unit
V _{IH}	Minimum High-Level Input Voltage	V_{out} = 0.1 V or V_{CC} – 0.1 V $ I_{out} \le 20 \mu A$	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V _{IL}	Maximum Low-Level Input Voltage	V_{out} = 0.1 V or V_{CC} – 0.1 V $ I_{out} \le 20 \mu A$	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	V
V _{OH}	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \ \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{in} = V_{IH}$ $ I_{out} \le 4.0 \text{ mA}$ $ I_{out} \le 5.2 \text{ mA}$	4.5 6.0	3.98 5.48	3.84 5.34	3.70 5.20	
V _{OL}	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \ \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{in} = V_{IH} \text{ or } V_{IL} \qquad \begin{vmatrix} I_{out} \end{vmatrix} \le 4.0 \text{ mA} \\ I_{out} \le 5.2 \text{ mA} \end{vmatrix}$	4.5 6.0	0.26 0.26	0.33 0.33	0.40 0.40	
l _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μΑ
Icc	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0 \mu A$	6.0	8	80	160	μΑ

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

			Gu	Guaranteed Limit		
Symbol	Parameter	v _{cc}	– 55 to 25°C	≤ 85 °C	≤ 125°C	Unit
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input D to Output Y (Figures 2 and 7)	2.0 4.5 6.0	170 34 29	215 43 37	255 51 43	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input D to Output ₹ (Figures 4 and 7)	2.0 4.5 6.0	185 37 31	230 46 39	280 56 48	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input D to Output Y (Figures 3 and 7)	2.0 4.5 6.0	185 37 31	230 46 39	280 56 48	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input A to Output ₹ (Figures 3 and 7)	2.0 4.5 6.0	205 41 35	255 51 43	310 62 53	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input D to Output Y (Figures 5 and 7)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Strobe to Output ₹ (Figures 6 and 7)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 2, 4 and 7)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C _{in}	Maximum Input Capacitance	_	10	10	10	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C _{PD}	Power Dissipation Capacitance (Per Package)	36	pF

PIN DESCRIPTIONS

INPUTS

D0, D1, ..., D7 (Pins 4, 3, 2, 1, 15, 14, 13, 12)

Data inputs. Data on any one of these eight binary inputs may be selected to appear on the output.

CONTROL INPUTS

A0, A1, A2 (Pins 11, 10, 9)

Address inputs. The data on these pins are the binary address of the selected input (see the Function Table).

Strobe (Pin 7)

Strobe. This input pin must be at a low level for the selected data to appear at the outputs. If the Strobe pin is high, the Y output is forced to a low level and the \overline{Y} output is forced to a high level.

OUTPUTS

Y, \(\overline{Y}\) (Pins 5, 6)

Data outputs. The selected data is presented at these pins in both true (Y output) and complemented (\overline{Y} output) forms.

SWITCHING WAVEFORMS

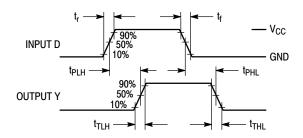


Figure 2.

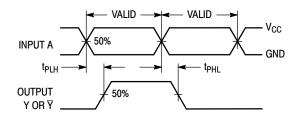


Figure 3.

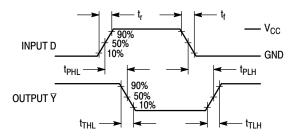


Figure 4.

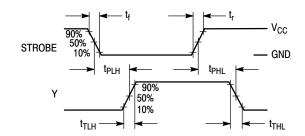


Figure 5.

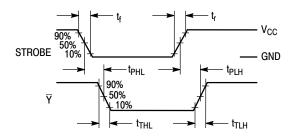
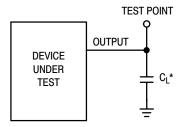


Figure 6.



*Includes all probe and jig capacitance

Figure 7. Test Circuit

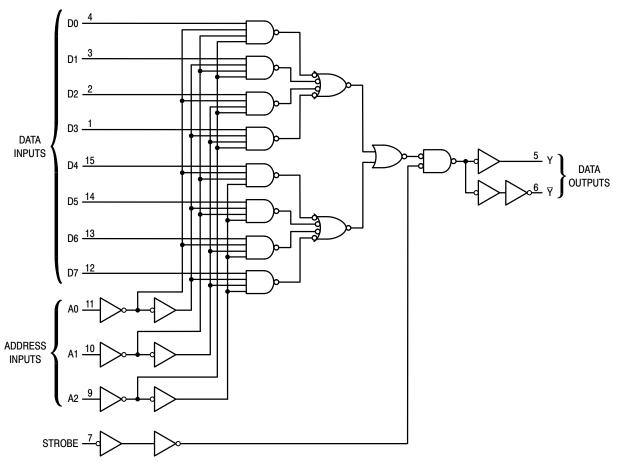


Figure 8. Expanded Logic Diagram

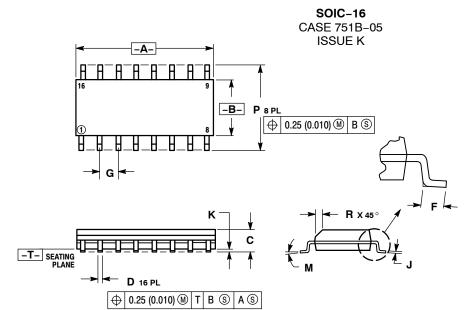
ORDERING INFORMATION

Device	Package	Shipping [†]
MC74HC151ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC151ADR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74HC151ADTR2G	TSSOP-16*	2500 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

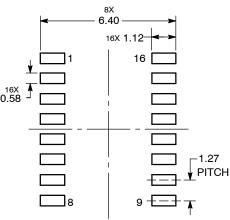
PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL RE 0.127 (0.005) TOTAL IN EXCESS OF THE D SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*

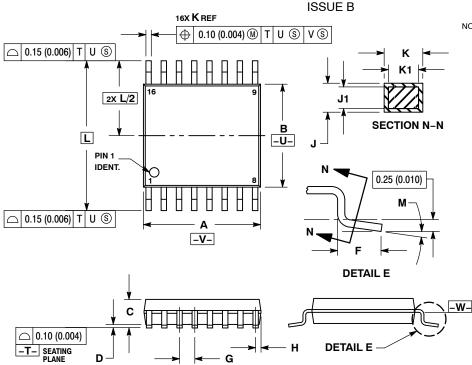


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** CASE 948F-01



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
 - ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS.
 - FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

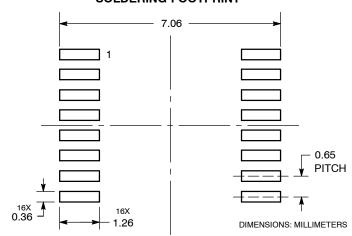
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K
 - (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL
 - DIMENSION AT MACHINON MALE LIFE
 CONDITION.

 6. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE
 DETERMINED AT DATUM PLANE.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
C		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.18	0.28	0.007	0.011
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252 BSC	
М	0 °	8°	0°	8 °

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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